

STM32WB07_QFN48_2L_IPD

MB2172

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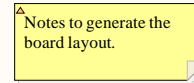
Sheet 2: STM32WB07_QFN48_RefBoard_IPD_2Layers

Legend

General comment such as function title, configuration, ...

Text to be added to silkscreen.

Warning text.



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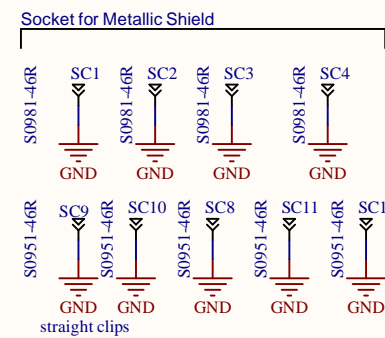
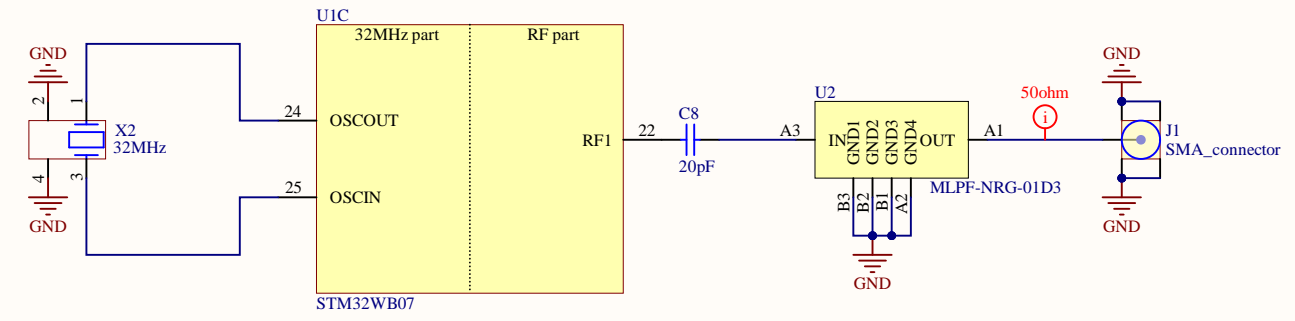
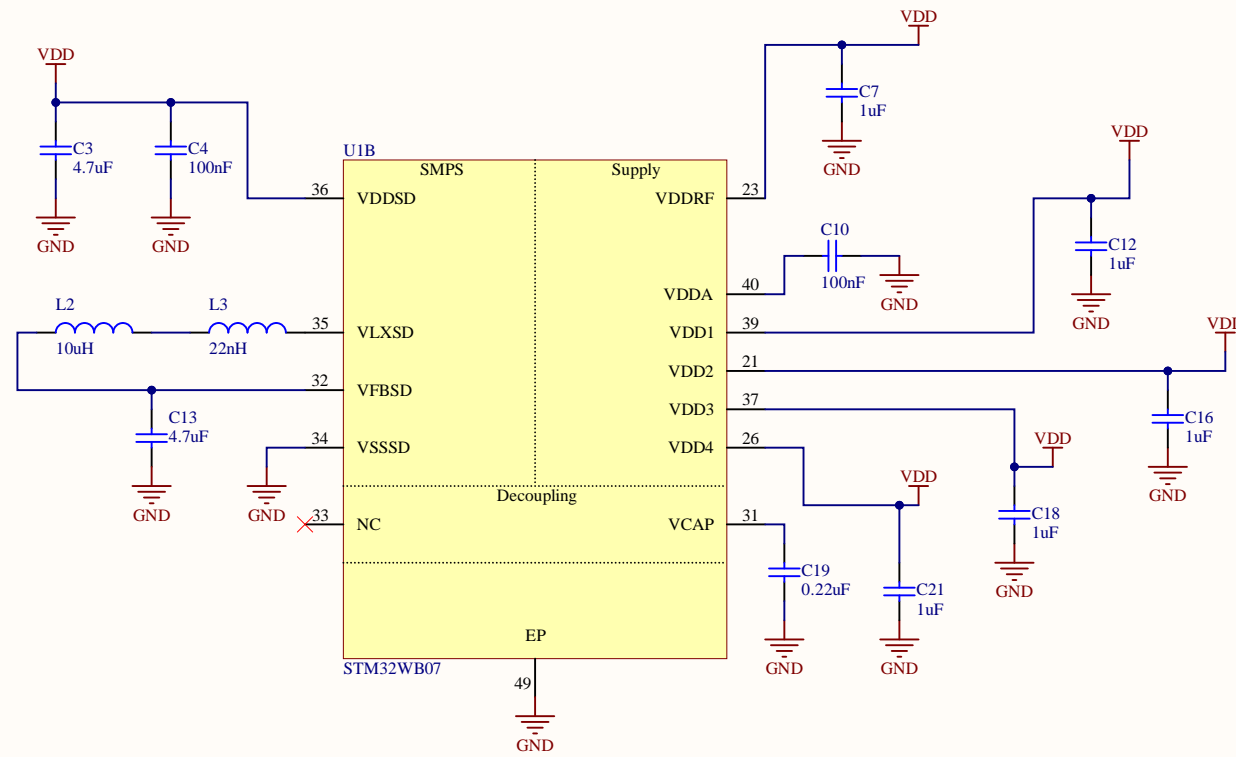
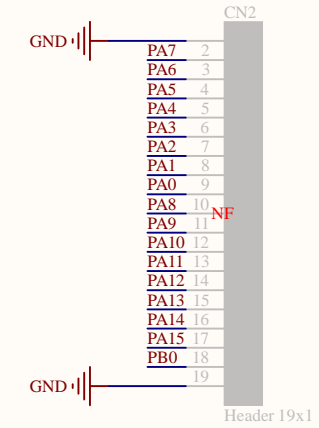
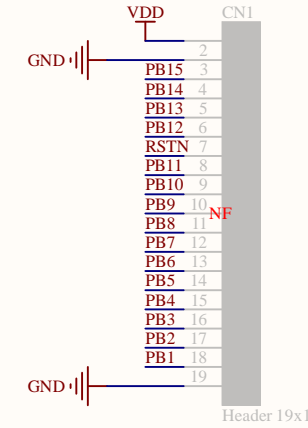
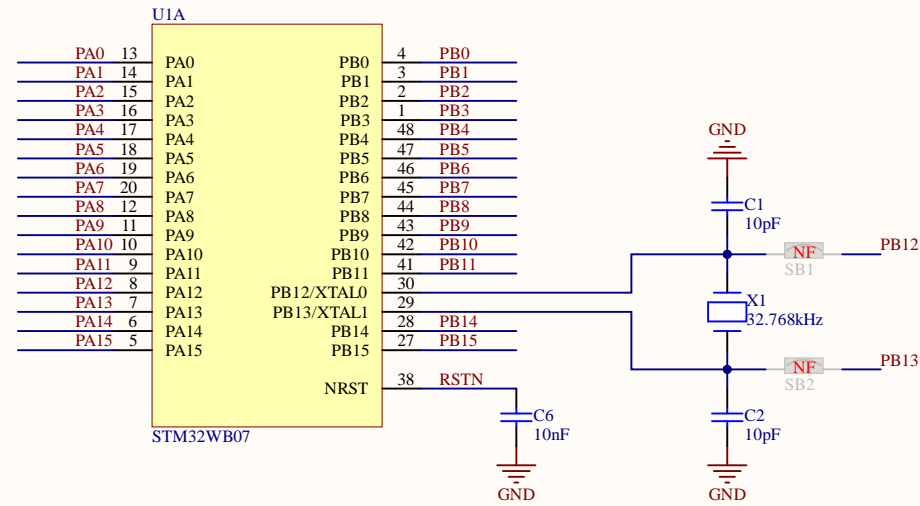
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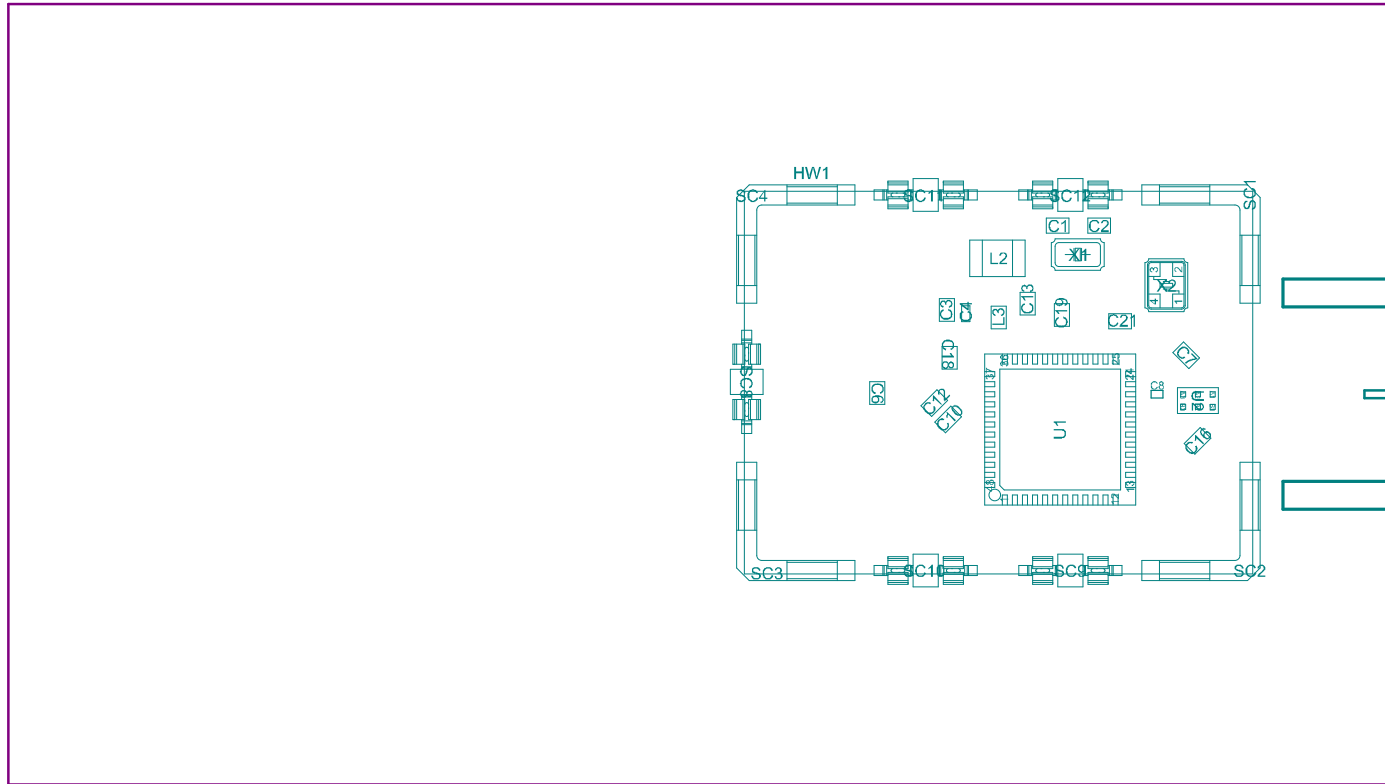
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Title: Project overview		
Project: STM32WB07_QFN48_2L_IPD		
Variant: Variant A		
Revision: A-01		Reference: MB2172
Size: A4	Date: 7 July 2024	Sheet: 1 of 7







Project: STM32WB07_QFN48_2L_IPD

Layer: Mechanical 14

Gerber: .GM14

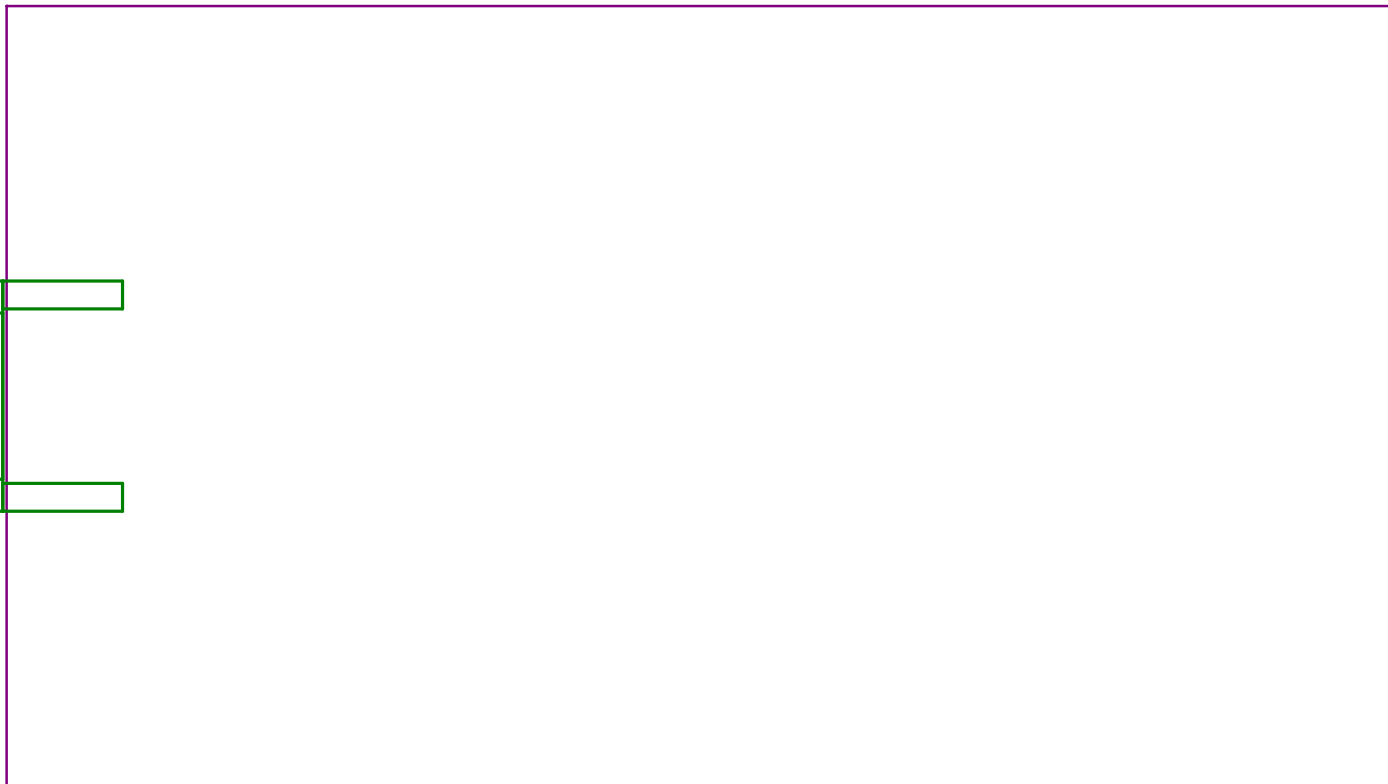
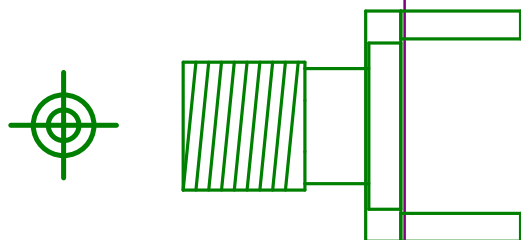
Variant: Variant A

Ref: MB2172

Date: 7 July 2024

Rev: A





Project: STM32WB07_QFN48_2L_IPD	
Layer: Mechanical 15	Gerber: .GM15
Variant: Variant A	Ref: MB2172
Date: 7 July 2024	Rev: A



